

L Number	Hits	Search Text	DB	Time stamp
1	2	("6555417").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 14:43
-	1986	MEMS and cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:50
-	128	(438/55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:26
-	188	(438/33).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:27
-	272	(438/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:27
-	168	(438/66).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:28
-	2320	(438/106).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:29
-	664	(438/126).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:30
-	1045	(438/118).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:31
-	271	(438/110).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:32
-	202	(438/51).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:32
-	593	(438/15).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:32
-	742	(216/2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:47
-	1737	MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:37

-	1436	MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3) and (cut\$3 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:47
-	215	(MEMS and (packag\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:39
-	63	(MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:47
-	286	(216/11).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:29
-	425	(216/17).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:48
-	909	(216/20).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:49
-	644	(216/24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:50
-	2311	MEMS and (cavity or recess)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:17
-	480	(216/33).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:56
-	123	(216/36).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:54
-	10	((216/33).CCLS.) and mems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 17:54
-	80	((438/25).CCLS.) or ((438/55).CCLS.) or ((438/33).CCLS.) or ((438/64).CCLS.) or ((438/66).CCLS.) or ((438/106).CCLS.) or ((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or ((438/51).CCLS.) or ((438/15).CCLS.)) and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:00
-	141	((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 12:46

-	215	(((((438/25).CCLS.) or ((438/55).CCLS.) or ((438/33).CCLS.) or ((438/64).CCLS.) or ((438/66).CCLS.) or ((438/106).CCLS.) or ((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or ((438/51).CCLS.) or ((438/15).CCLS.)) and MEMS) or (((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:00
-	20	((wafer adj bonding) or (wafer adj cap\$4)).ti. and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:18
-	1567	MEMS and (cavity or recess) and cap\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:37
-	49	MEMS and (cavity or recess) and (wafer adj cap\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:20
-	99	MEMS and (cavity or recess) and (wafer near3 cap\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:27
-	27	(MEMS and package).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:28
-	803	(257/433).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:31
-	816	(257/443).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:32
-	1596	((257/433).CCLS.) or ((257/443).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:33
-	561	(257/466).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:34
-	334	MEMS and (cavity or recess) and cap\$4 and dic\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 18:37
-	2	("5323051").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 19:07
-	154	(438/25).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:17

-	647	MEMS and (cavity or cavities) and (cap or capped or capping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:17
-	111	MEMS with (cap or capped or capping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:40
-	56	MEMS and (cap or capped or capping) same (diced or dicing or dice)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:53
-	15	(MEMS and (cap or capped or capping) and (diced or dicing or dice)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 10:25
-	11	("4742432" "4889587" "5230759" "5656776" "5798557" "5824177" "5915168" "5923995" "6136212" "6255741" "6379988").PN.	USPAT	2004/01/08 15:47
-	886	(438/108).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:54
-	674	(438/113).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:54
-	920	(438/127).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 15:55
-	62	(MEMS and (cap or capped or capping)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 12:48
-	18	(wafer adj cap\$4).ab. and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 12:46
-	23	((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.) and MEMS and (cap or capping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 12:47
-	21	((MEMS or microstructure\$1 or micromechanical or microelectromechanical) and (cap or capped or capping)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 12:49